

## General Description

FSMOS<sup>®</sup> MOSFET is based on Oriental Semiconductor's unique device design to achieve low  $R_{DS(ON)}$ , low gate charge, fast switching and excellent avalanche characteristics. The low  $V_{th}$  series is specially optimized for synchronous rectification systems with low driving voltage.

## Features

- Low  $R_{DS(on)}$  & FOM (Figure of Merit)
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery



## Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switched mode power supply

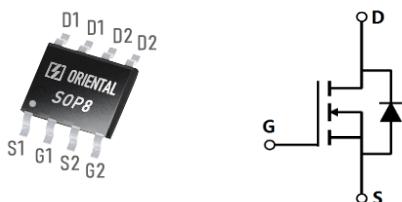
## Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_{j(max)}$	80	V
$I_D, pulse$	48	A
$R_{DS(ON) max} @ V_{GS}=10V$	8	mΩ
$Q_g$	28.9	nC

## Marking Information

Product Name	Package	Marking
SFS08R08BF	SOP8	SFS08R08B

## Package & Pin information



**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	$V_{DS}$	80	V
Gate source voltage	$V_{GS}$	$\pm 20$	V
Continuous drain current <sup>1)</sup> , $T_C=25^\circ\text{C}$	$I_D$	16	A
Pulsed drain current <sup>2)</sup> , $T_C=25^\circ\text{C}$	$I_{D,\text{pulse}}$	48	A
Continuous diode forward current <sup>1)</sup> , $T_C=25^\circ\text{C}$	$I_S$	16	A
Diode pulsed current <sup>2)</sup> , $T_C=25^\circ\text{C}$	$I_{S,\text{Pulse}}$	48	A
Power dissipation <sup>3)</sup> , $T_C=25^\circ\text{C}$	$P_D$	8	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	25	mJ
Operation and storage temperature	$T_{\text{stg}}, T_j$	-55 to 175	$^\circ\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-ambient <sup>4)</sup>	$R_{\theta JA}$	62	$^\circ\text{C/W}$

**Electrical Characteristics** at  $T_j=25^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	80			V	$V_{GS}=0 \text{ V}, I_D=250 \text{ uA}$
Gate threshold voltage	$V_{GS(\text{th})}$	1.0		2.5	V	$V_{DS}=V_{GS}, I_D=250 \text{ uA}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		7.1	8	$\text{m}\Omega$	$V_{GS}=10 \text{ V}, I_D=12 \text{ A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		8.2	10	$\text{m}\Omega$	$V_{GS}=4.5 \text{ V}, I_D=9 \text{ A}$
Gate-source leakage current	$I_{GSS}$			100	nA	$V_{GS}=20 \text{ V}$
				-100		$V_{GS}=-20 \text{ V}$
Drain-source leakage current	$I_{DSS}$			1	uA	$V_{DS}=80 \text{ V}, V_{GS}=0 \text{ V}$
Gate resistance	$R_G$		3.3		$\Omega$	$f=1 \text{ MHz}, \text{Open drain}$

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C <sub>iss</sub>		2028		pF	V <sub>GS</sub> =0 V, V <sub>DS</sub> =25 V, f=100 kHz
Output capacitance	C <sub>oss</sub>		717		pF	
Reverse transfer capacitance	C <sub>rss</sub>		53.9		pF	
Turn-on delay time	t <sub>d(on)</sub>		22.2		ns	V <sub>GS</sub> =10 V, V <sub>DS</sub> =50 V, R <sub>G</sub> =2.5 Ω, I <sub>D</sub> =25 A
Rise time	t <sub>r</sub>		6.3		ns	
Turn-off delay time	t <sub>d(off)</sub>		47.5		ns	
Fall time	t <sub>f</sub>		8.8		ns	

### Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q <sub>g</sub>		28.9		nC	V <sub>GS</sub> =10 V, V <sub>DS</sub> =50 V, I <sub>D</sub> =25 A
Gate-source charge	Q <sub>gs</sub>		5.4		nC	
Gate-drain charge	Q <sub>gd</sub>		4.9		nC	
Gate plateau voltage	V <sub>plateau</sub>		3.5		V	

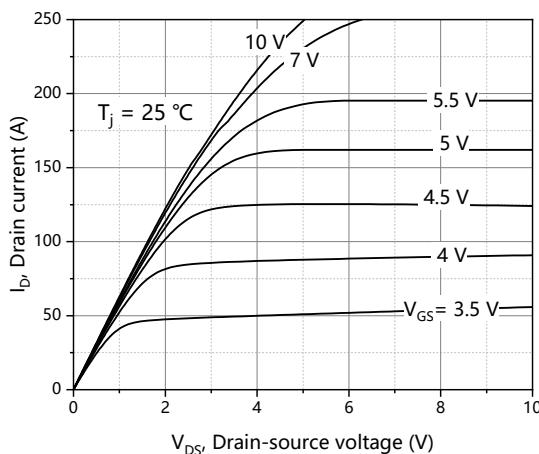
### Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V <sub>SD</sub>			1.3	V	I <sub>S</sub> =12 A, V <sub>GS</sub> =0 V
Reverse recovery time	t <sub>rr</sub>		51.3		ns	V <sub>R</sub> =50 V, I <sub>S</sub> =25 A, di/dt=100 A/μs
Reverse recovery charge	Q <sub>rr</sub>		60.6		nC	
Peak reverse recovery current	I <sub>rrm</sub>		2		A	

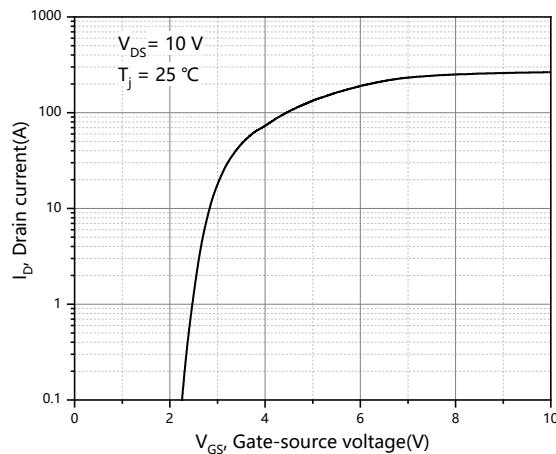
### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25 °C.
- 5) V<sub>DD</sub>=50 V, V<sub>GS</sub>=10 V, L=0.3 mH, starting T<sub>j</sub>=25 °C.

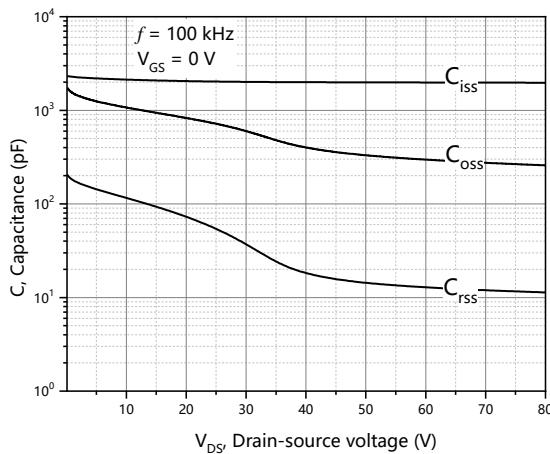
### Electrical Characteristics Diagrams



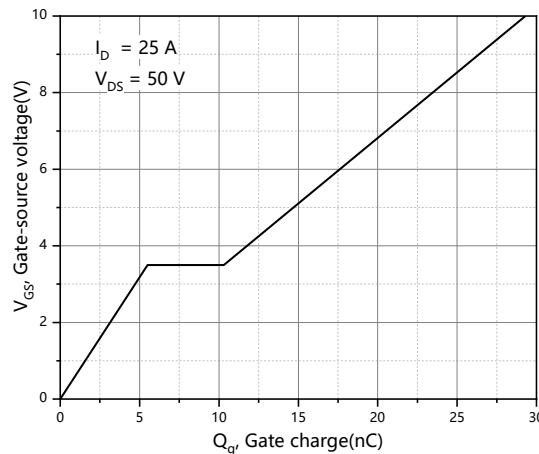
**Figure 1. Typ. output characteristics**



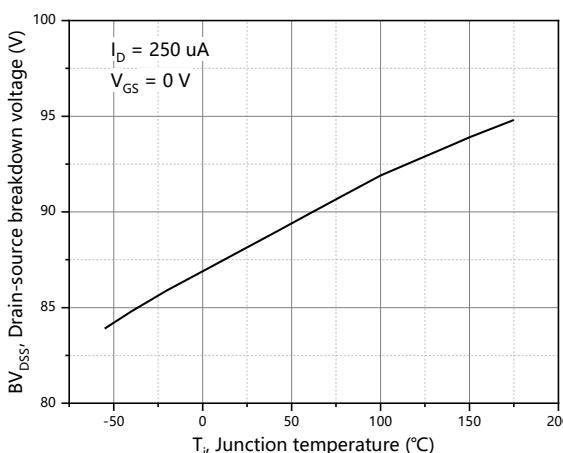
**Figure 2. Typ. transfer characteristics**



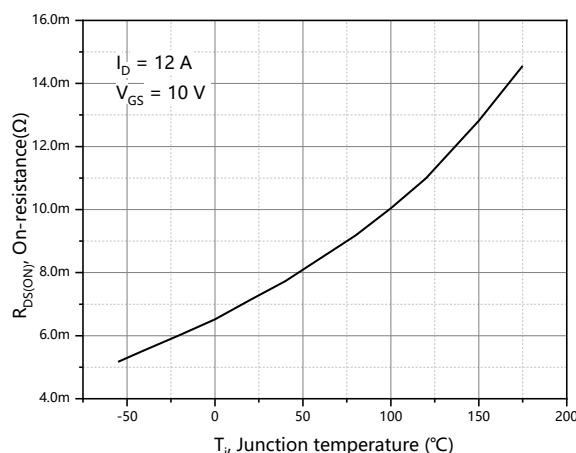
**Figure 3. Typ. capacitances**



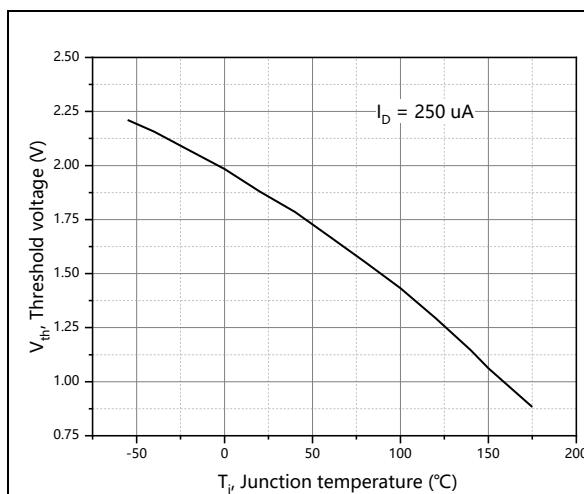
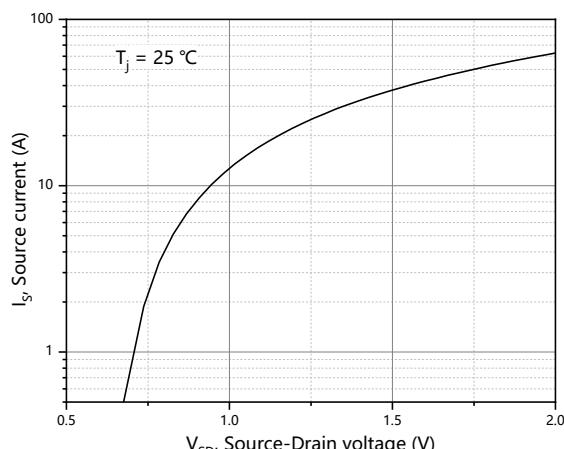
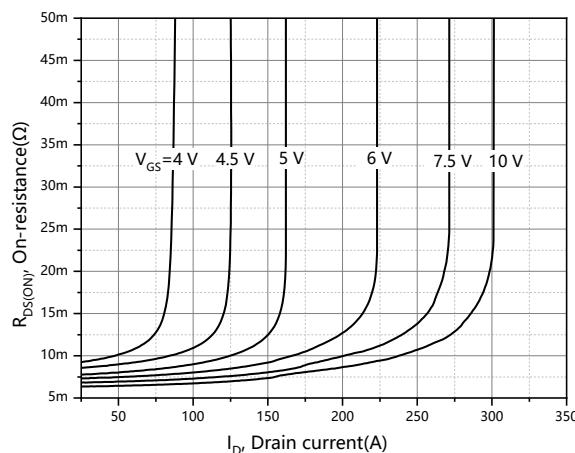
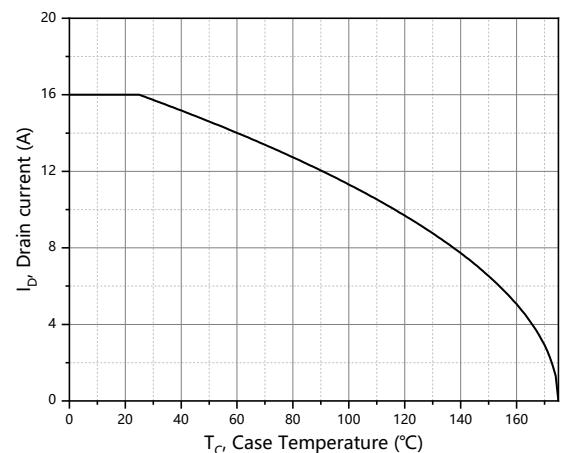
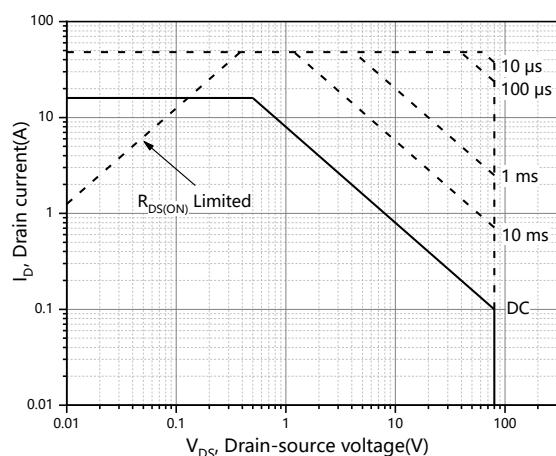
**Figure 4. Typ. gate charge**



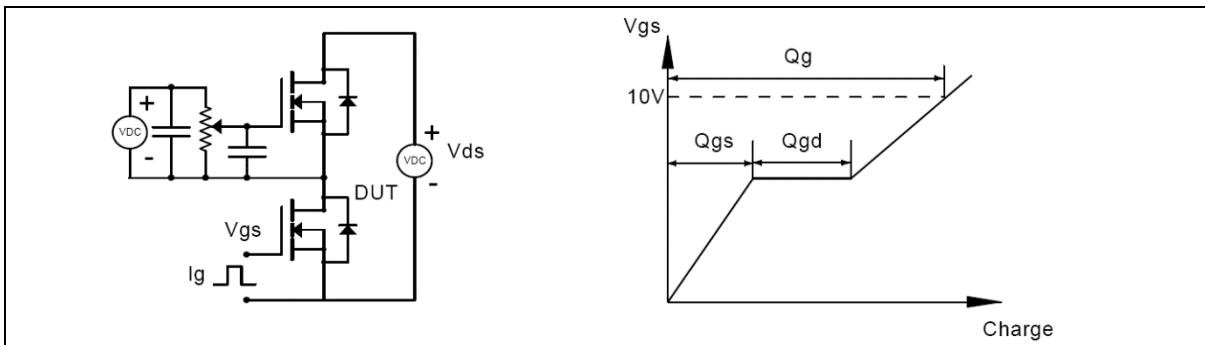
**Figure 5. Drain-source breakdown voltage**



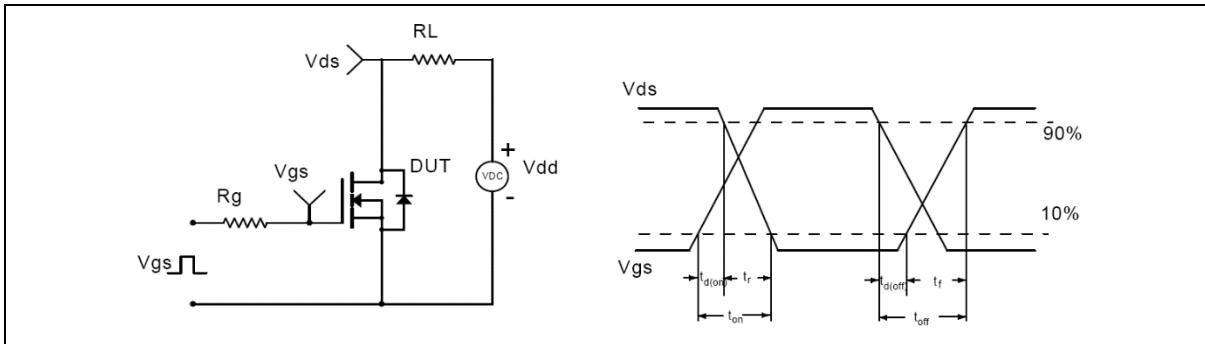
**Figure 6. Drain-source on-state resistance**


**Figure 7. Threshold voltage**

**Figure 8. Forward characteristic of body diode**

**Figure 9. Drain-source on-state resistance**

**Figure 10. Drain current**

**Figure 11. Safe operation area  $T_c=25^\circ C$**

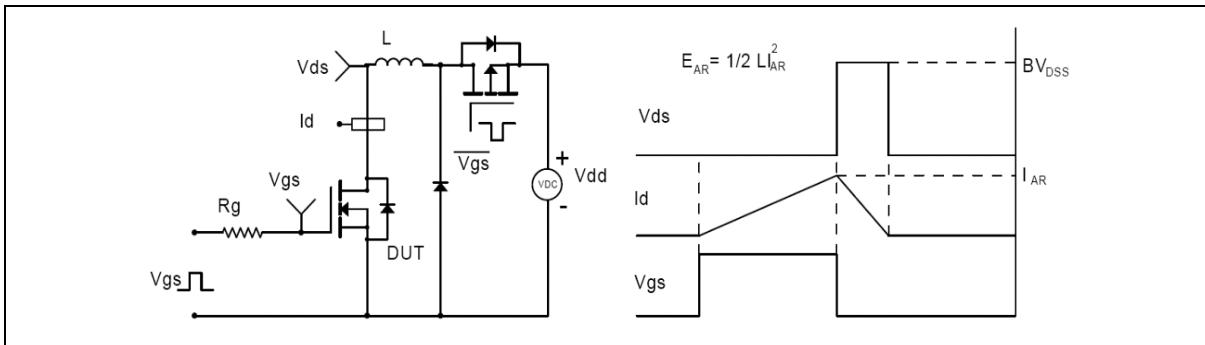
### Test circuits and waveforms



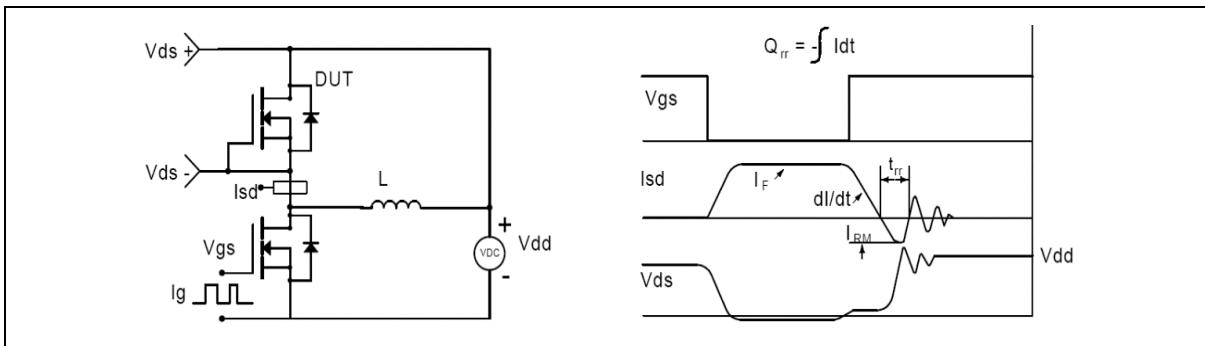
**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**

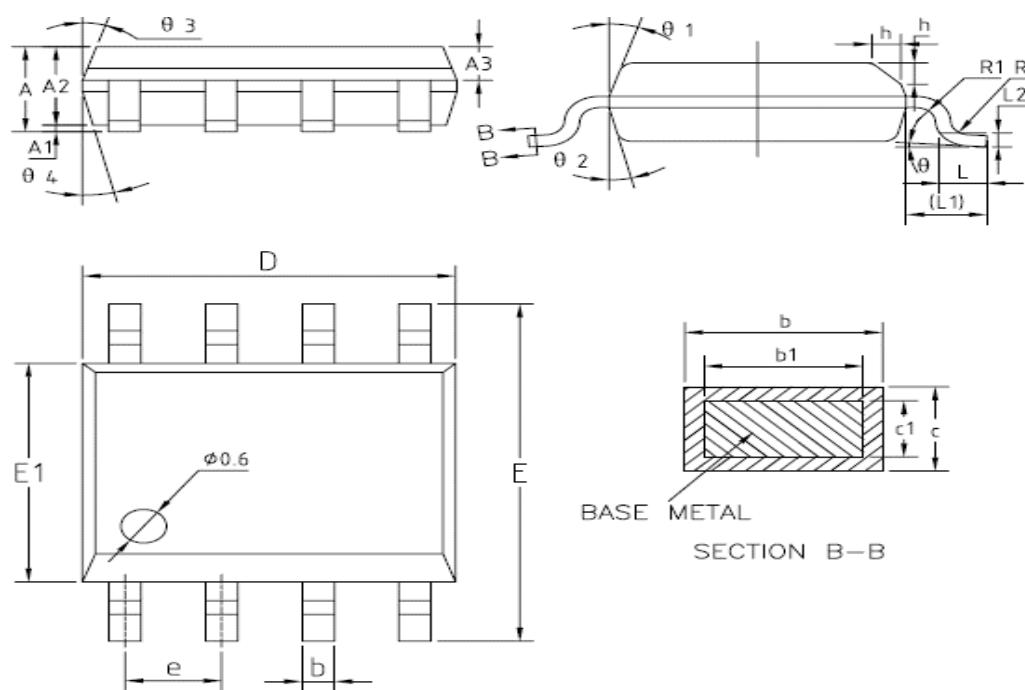


**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

### Package Information



Symbol	mm		
	Min	Nom	Max
A	1.35	1.55	1.75
A1	0.10	0.15	0.25
A2	1.25	1.40	1.65
A3	0.50	0.60	0.70
b	0.38	-	0.51
L1	1.04 REF		
L2	0.25 BSC		
b1	0.37	0.42	0.47
c	0.18	-	0.25
c1	0.17	0.20	0.23
D	4.80	4.90	5
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e	1.17	1.27	1.37
L	0.45	0.60	0.80
R	0.07	-	-
R1	0.07	-	-
h	0.30	0.40	0.50
θ	0°	-	8°
θ1	15°	17°	19°
θ2	11°	13°	15°
θ3	15°	17°	19°
θ4	11°	13°	15°

Version 1: SOP8-K package outline dimension

## Ordering Information

Package Type	Units/Reel	Reels / Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
SOP8-K	2500	2	5000	6	30000

## Product Information

Product	Package	Pb Free	RoHS	Halogen Free
SFS08R08BF	SOP8	yes	yes	yes

## Legal Disclaimer

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